

WHAT IS CLAIMED IS:

1. An exposure apparatus comprising:
an optical system for guiding light from a
5 light source to an object;
a holding member for holding the object; and
a measuring device for measuring position of
the holding member by using a reference surface
provided in the holding member, wherein the reference
10 surface is located in an area corresponding to the
object which is held by the holding member.
2. The exposure apparatus according to claim 1,
wherein the reference surface is located substantially
15 at a position corresponding to the center of the object
which is held by the holding member.
3. The exposure apparatus according to claim 1,
wherein the position substantially corresponding to the
20 center of the object is fixed to a position
substantially corresponding to the center of the
holding member.
4. The exposure apparatus according to claim 1,
25 wherein the object is a reticle.

5. The exposure apparatus according to claim 1,
wherein the object is a wafer.

6. The exposure apparatus according to claim 1,
5 wherein the holding member holds the object by
electrostatic suction.

7. The exposure apparatus according to claim 1,
exposes the object by scanning the object.

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8. The exposure apparatus according to claim 1,
wherein the light source is an EUV light source.

9. An exposure method comprising the steps of:
15 measuring position of an object founding on a
reference surface being provided in a holding member
which holds the object, the reference surface being
located in an area corresponding to the object,
adjusting the position of the object in
20 accordance with the measurement results; and
exposing the object by guiding light from a
light source to the object.

10. A device fabrication method comprising the
25 steps of:
exposing an object by an exposure apparatus
which comprises an optical system for guiding light

from a light source to an object, a holding member for holding the object, and a measuring device for measuring position of the holding member by using a reference surface provided in the holding member,
5 wherein the reference surface is located in an area corresponding to the object which is held by the holding member; and
developing the object that has been exposed.